IEEE HOME I SEARCH IEEE I SHOP I WEB ACCOUNT I CONTACT IEEE



	IEEE Peer	Quick Links		» Search Results					
view Icome to IEEE <i>Xplore</i>		matched 379 of 940663 de	ocuments.						
		of 379 results are displayed		nublication year in					
I Access?	ascending of	order.		•					
O- Log-out	text box.	me your search by editing ti	ie current search express	on or entering a new one the					
ables of Contents		earch Again.	4						
O- Journals & Magazines	[(microproces	ssor* or "integrated circuit*")	and "therm . Search Aga						
O- Conference Proceedings	Results:	i TNU Conforma	ONE Charles OTE						
O- Standards	Journal or Ma	agazine = JNL Conference	= CNF Standard = SIL						
earch	1 VLSI T	hermal Management	in Cost Driven Syste	ems					
O- By Author	Lewis, T.; Adams, D.; Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see								
O- Basic	also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part								
O- Advanced	1 ' ' ' '	Volume: 5 Issue: 4, De	ec 1982						
Aember Services	Page(s):	361-36/							
O- Join IEEE									
O- Establish IEEE Web Account	[Abstract] [PDF Full-Text (1544 KB)] IEEE JNL								
O- Access the	2 Alumin	um Nitrida-An Altern	ative Ceramic Subs	trate for High Power					
IEEE Member Digital Library	2 Aluminum Nitride-An Alternative Ceramic Substrate for High Power Applications in Microcircuits								
Print Format		er, W.; Aldinger, F.;	facturing Tachnology	IEEE Transactions on Issa					
_	Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 7 Issue: 4, Dec 1984								
						Page(s):	399 -404		
	[Abstract] [PDF Full-Text (1048 KB)] IEEE JNL								
	3 Thermal Characteristics of Plastic Small Outline Transistor (SOT) Packages Alli, M.; Mahalingam, M.; Andrews, J.; Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part								
							Volume: 9 Issue: 4, De		
						Page(s):	353 -363		

1 of 10



4 Thermal Management of Air- and Liquid-Cooled Multichip Modules

Bar-Cohen, A.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 10 Issue: 2, Jun 1987

Page(s): 159 -175

[Abstract] [PDF Full-Text (2704 KB)] IEEE JNL

5 Advances in IC packaging, interconnect and assembly

Sage, M.;

Electronic Manufacturing Technology Symposium, 1988, Fourth IEEE/CHMT European International, 13-15 Jun 1988

Page(s): 76 -79

[Abstract] [PDF Full-Text (176 KB)] IEEE CNF

6 Thermal advantages of a new microcircuit configuration

Pestorius, T.D.; Gregory, V.; Kraus, A.D.;

Thermal Phenomena in the Fabrication and Operation of Electronic Components:

I-THERM '88, InterSociety Conference on , 11-13 May 1988

Page(s): 33 -36

[Abstract] [PDF Full-Text (256 KB)] IEEE CNF

7 Thermal management of a high-performance multichip module

Chen, C.C.; Young, P.L.; Cech, J.M.;

Electronics Components Conference, 1988., Proceedings of the 38th, 9-11 May

1988

Page(s): 302 -304

[Abstract] [PDF Full-Text (1072 KB)] IEEE CNF

8 Internal thermal resistance of a multi-chip packaging design for VLSI-based systems

Lee, Y.C.; Ghaffari, H.T.; Segelken, J.M.;

Electronics Components Conference, 1988., Proceedings of the 38th, 9-11 May

1988

Page(s): 293 -301

[Abstract] [PDF Full-Text (528 KB)] IEEE CNF

9 Design of high-frequency hybrid power transformer

Gradzki, P.M.; Lee, F.C.;

Applied Power Electronics Conference and Exposition, 1988. APEC '88.

Conference Proceedings 1988., Third Annual IEEE , 1-5 Feb 1988

Page(s): 319 -326



[Abstract] [PDF Full-Text (552 KB)] IEEE CNF

10 An Addendum and Correction to "Thermal Management of Air- and Liquid-Cooled Multichip Modules"

Bar-Cohen, A.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 11 Issue: 3, Sep 1988

Page(s): 333 -334

[Abstract] [PDF Full-Text (192 KB)] IEEE JNL

11 Cooling techniques in electronics

Johnson, R.D.;

Thermal Design of Electronic Systems, IEE Colloquium on , 29 Mar 1989

Page(s): 5/1 -5/4

[Abstract] [PDF Full-Text (140 KB)] IEE CNF

12 Quality issues of high pin count fine pitch VLSI packages

Hnatek, E.R.; Livesay, B.R.;

Test Conference, 1989. Proceedings. 'Meeting the Tests of Time'., International,

29-31 Aug 1989

Page(s): 397 -421

[Abstract] [PDF Full-Text (1372 KB)] IEEE CNF

13 Packaging for a 1 Gb/s OEIC fiber-optic data link

Jackson, K.P.; Flint, E.B.; Cina, M.F.; Moll, A.J.; Ewen, J.F.; Flagello, D.; Rand, R.; Purushothaman, S.;

Electronic Components Conference, 1989. Proceedings., 39th, 22-24 May 1989 Page(s): 374 -377

[Abstract] [PDF Full-Text (312 KB)] IEEE CNF

14 3-D wafer-scale interconnect and packaging using photosensitive glass-ceramic substrates

Jacobi, W.J.; Reche, J.J.H.;

Aerospace and Electronics Conference, 1989. NAECON 1989., Proceedings of the IEEE 1989 National, 22-26 May 1989

Page(s): 4 -8 vol.1

[Abstract] [PDF Full-Text (264 KB)] IEEE CNF

15 Internal thermal resistance of a multi-chip packaging design for VLSI based systems

Lee, Y.C.; Ghaffari, H.T.; Segelken, J.M.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see



also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part

A, B, C], Volume: 12 Issue: 2, Jun 1989

Page(s): 163 -169

[Abstract] [PDF Full-Text (632 KB)] IEEE JNL

16 INTELEC: Twelfth International Telecommunications Energy Conference (Cat. No.90CH2928-0)

Telecommunications Energy Conference, 1990. INTELEC '90., 12th International, 21-25 Oct 1990

[Abstract] [PDF Full-Text (360 KB)] IEEE CNF

17 Low Tg epoxy adhesives for thermal management

Chung, K.K.T.; Avery, E.; Boyle, A.; Dreier, G.; Koehn, W.; Govaert, G.; Theunissen, D.;

Electronic Manufacturing Technology Symposium, 1990, IEMT Conference., 8th IEEE/CHMT International , 7-9 May 1990

Page(s): 264 -277

[Abstract] [PDF Full-Text (440 KB)] IEEE CNF

18 Design of HWSI multichip modules for quick prototyping and manufacturing

Lee, Y.C.;

Electronic Components and Technology Conference, 1990. Proceedings., 40th, 20-23 May 1990

Page(s): 586 -591 vol.1

[Abstract] [PDF Full-Text (388 KB)] IEEE CNF

19 Development of robust hybrids for smart skin avionics

Thomas, T.L.;

Electronic Components and Technology Conference, 1990. Proceedings., 40th, 20-23 May 1990

Page(s): 131 -139 vol.1

[Abstract] [PDF Full-Text (636 KB)] IEEE CNF

20 Low temperature co-fired glass-ceramic, high-density-interconnect, substrate with improved thermal management

Rich, E.L., III; Martin, A.J.; Lengel, T.M.; Stewart, J.J.; Gallo, S.A.; Electronic Components and Technology Conference, 1990. Proceedings., 40th, 20-23 May 1990

Page(s): 122 -130 vol.1

[Abstract] [PDF Full-Text (688 KB)] IEEE CNF



21 Silicon interconnect-a critical factor in device thermal management

Witzman, S.; Metelski, G.; Smith, K.;

Thermal Phenomena in Electronic Systems, 1990. I-THERM II., InterSociety

Conference on , 23-25 May 1990

Page(s): 154 -160

[Abstract] [PDF Full-Text (756 KB)] IEEE CNF

22 Low temperature co-fired glass ceramic high density interconnect substrate with improved thermal management

Rich, E.L., III; Martin, A.J.; Lengel, T.M.; Stewart, J.J.; Gallo, S.A.; Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 13 Issue: 4, Dec 1990

Page(s): 639 -646

[Abstract] [PDF Full-Text (712 KB)] IEEE JNL

23 Silicon interconnect-a critical factor in device thermal management

Witzman, S.; Smith, K.; Metelski, G.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C], Volume: 13 Issue: 4, Dec 1990

Page(s): 946 -952

[Abstract] [PDF Full-Text (556 KB)] IEEE JNL

24 Hybrid technologies for high frequency switching power supplies

Belopolsky, Y.: Dassatti, R.:

Electronic Components and Technology Conference, 1991. Proceedings., 41st,

11-16 May 1991

Page(s): 103 -108

[Abstract] [PDF Full-Text (468 KB)] IEEE CNF

25 Factors in implementing MCM solutions for the high performance systems of the 1990s

Buschbom, M.L.; Calvin, S.E.;

Custom Integrated Circuits Conference, 1991., Proceedings of the IEEE 1991,

12-15 May 1991

Page(s): 27.1/1 -27.1/4

[Abstract] [PDF Full-Text (308 KB)] IEEE CNF

26 GaAs HBTs: an analog circuit design perspective

Corcoran, J.; Poulton, K.; Knudsen, K.;

Bipolar Circuits and Technology Meeting, 1991., Proceedings of the 1991, 9-10

Sep 1991

Page(s): 245 -252

[Abstract] [PDF Full-Text (712 KB)] IEEE CNF

27 Hybrid packaging technique for high power density circuit

Ngon Binh Nguyen; Jones, F.B.;

Semiconductor Thermal Measurement and Management Symposium, 1991. SEMI-THERM VII. Proceedings., Seventh Annual IEEE, 12-14 Feb 1991

Page(s): 105 -109

[Abstract] [PDF Full-Text (212 KB)] IEEE CNF

28 1991 Proceedings, Seventh Annual IEEE Semiconductor Thermal Measurement and Management Symposium (Cat. No.91CH2972-8) Semiconductor Thermal Measurement and Management Symposium, 1991.

Semiconductor Thermal Measurement and Management Symposium, 199. SEMI-THERM VII. Proceedings., Seventh Annual IEEE , 12-14 Feb 1991

[Abstract] [PDF Full-Text (24 KB)] IEEE CNF

29 Thermal modeling and analysis of pin grid arrays and multichip modules

Sullhan, R.; Fredholm, M.; Monaghan, T.; Agarwal, A.; Kozarek, B.; Semiconductor Thermal Measurement and Management Symposium, 1991. SEMI-THERM VII. Proceedings., Seventh Annual IEEE, 12-14 Feb 1991 Page(s): 110 -116

[Abstract] [PDF Full-Text (520 KB)] IEEE CNF

30 Eighth Annual IEEE Semiconductor Thermal Measurement and Management Symposium (Cat. No.92CH3095-7)

Semiconductor Thermal Measurement and Management Symposium, 1992. SEMI-THERM VIII., Eighth Annual IEEE, 3-5 Feb 1992

[Abstract] [PDF Full-Text (24 KB)] IEEE CNF

31 The technology for over 300-pin QFPs

Shirai, Y.; Otsuka, K.; Okinaga, T.; Suzuki, H.; Murakami, G.; Arai, K.; Satuu, Y.; Emata, T.; Matsunaga, T.;

Electronic Components and Technology Conference, 1992. Proceedings., 42nd , 18-20 May 1992

Page(s): 423 -428

[Abstract] [PDF Full-Text (420 KB)] IEEE CNF

32 Multichip module enables for high reliability applications

Chu, D.; Reber, C.A.; Draper, B.L.; Sweet, J.N.; Palmer, D.W.; Multi-Chip Module Conference, 1992. MCMC-92, Proceedings 1992 IEEE, 18-20 Mar 1992

Page(s): 102 -105

[Abstract] [PDF Full-Text (328 KB)] IEEE CNF

33 Thermal management for ceramic multichip modules: experimental program

Kromann, G.B.;

Multi-Chip Module Conference, 1992. MCMC-92, Proceedings 1992 IEEE, 18-20

Mar 1992

Page(s): 75 - 78

[Abstract] [PDF Full-Text (352 KB)] IEEE CNF

34 Proceedings. 1992 IEEE Multi-Chip Module Conference MCMC-92 (Cat. No.92CH3124-5)

Multi-Chip Module Conference, 1992. MCMC-92, Proceedings 1992 IEEE, 18-20 Mar 1992

[Abstract] [PDF Full-Text (36 KB)] IEEE CNF

35 Wide band-gap semiconductor: how good is diamond?

Chalker, P.R.:

Diamond in Electronics and Optics, IEE Colloquium on , 4 Nov 1993

Page(s): 1/1 -1/3

[Abstract] [PDF Full-Text (136 KB)] **IEE CNF**

36 Viking SuperSPARC AMCM development program

Eichelberger, C.W.; Davidson, H.;

Multi-Chip Module Conference, 1993. MCMC-93, Proceedings., 1993 IEEE, 15-18

Mar 1993

Page(s): 29 -32

[Abstract] [PDF Full-Text (344 KB)] **IEEE CNF**

37 High density overlay interconnect (HDI) delivers high frequency performance for GaAs systems

Gdula, M.; Haller, T.; Krishnamurthy, V.; Forman, G.;

Multi-Chip Module Conference, 1993. MCMC-93, Proceedings., 1993 IEEE, 15-18

Mar 1993

Page(s): 33 -38

[Abstract] [PDF Full-Text (524 KB)] **IEEE CNF**

38 The GE high density overlay MCM interconnect method solves high power needs of GaAs system design

Gdula, M.; Yerman, A.; Krishnamurthy, V.; Fillion, R.;

Wafer Scale Integration, 1993. Proceedings., Fifth Annual IEEE International Conference on , 20-22 Jan 1993

Page(s): 339 -345

[Abstract] [PDF Full-Text (400 KB)] IEEE CNF

39 Ninth Annual IEEE Semiconductor Thermal Measurement and Management Symposium (Cat. No.93CH3226-8)

Semiconductor Thermal Measurement and Management Symposium, 1993. SEMI-THERM IX., Ninth Annual IEEE , 2-4 Feb 1993

[Abstract] [PDF Full-Text (24 KB)] IEEE CNF

40 Effect of molding compound thermal conductivity on thermal performance of molded multi-chip modules

Azar, K.; Mandrone, C.D.; Segelken, J.M.; Semiconductor Thermal Measurement and Management Symposium, 1993. SEMI-THERM IX., Ninth Annual IEEE, 2-4 Feb 1993 Page(s): 19 -27

[Abstract] [PDF Full-Text (472 KB)] IEEE CNF

41 Trends in low-cost, high-performance substrate technology

Carey, D.H.;

Micro, IEEE, Volume: 13 Issue: 2, Apr 1993

Page(s): 19 -27

[Abstract] [PDF Full-Text (776 KB)] IEEE JNL

42 Addressing the challenges of advanced packaging and interconnection

Herrell, D.J.;

Micro, IEEE, Volume: 13 Issue: 2, Apr 1993

Page(s): 10 -18

[Abstract] [PDF Full-Text (808 KB)] IEEE JNL

43 Electrical performance of flip-chip PBGA vs. CBGA

Sarfaraz, A.; Tai-Yu Chou; Omer, A.; Nealon, M.; Poehang Hsu; Khalili, S.; Electrical Performance of Electronic packaging, 1994., IEEE 3rd Topical Meeting on , 2-4 Nov 1994 Page(s): 14-17

[Abstract] [PDF Full-Text (328 KB)] IEEE CNF

44 Fabrication technology for wafer through-hole interconnections and three-dimensional stacks of chips and wafers

Linder, S.; Baltes, H.; Gnaedinger, F.; Doering, E.; Micro Electro Mechanical Systems, 1994, MEMS '94, Proceedings, IEEE Workshop on , 1994

Page(s): 349 -354

[Abstract] [PDF Full-Text (1028 KB)] IEEE CNF

45 A hybrid-circuit tile-approach architecture for high-power spatial power-combined transmitters

Gouker, M.A.; Beaudette, R.G.; Delisle, J.T.; Microwave Symposium Digest, 1994., IEEE MTT-S International, 23-27 May 1994

Page(s): 1545 -1548 vol.3

[Abstract] [PDF Full-Text (446 KB)] IEEE CNF

46 A hybrid-circuit tile-approach architecture for high-power spatial power-combined transmitters

Gouker, M.A.; Beaudette, R.G.; Delisle, J.T.;
Telesystems Conference, 1994. Conference Proceedings., 1994 IEEE National, 26-28 May 1994
Page(s): 47-50

[Abstract] [PDF Full-Text (360 KB)] IEEE CNF

47 A study on the evaporation heat transfer in the cooling of high power electronics

Kristiansen, H.; Fallet, T.; Bjorneklett, A.; Semiconductor Thermal Measurement and Management Symposium, 1994. SEMI-THERM X., Proceedings of 1994 IEEE/CPMT 10th, 1-3 Feb 1994 Page(s): 114-120

[Abstract] [PDF Full-Text (576 KB)] IEEE CNF

48 Proceedings of 1994 IEEE/CHMT 10th Semiconductor Thermal Measurement and Management Symposium (SEMI-THERM)

Semiconductor Thermal Measurement and Management Symposium, 1994. SEMI-THERM X., Proceedings of 1994 IEEE/CPMT 10th , 1-3 Feb 1994

[Abstract] [PDF Full-Text (20 KB)] IEEE CNF

49 A hi-density C4/CBGA interconnect technology for a CMOS microprocessor

Kromann, G.; Gerke, D.; Huang, W.; Electronic Components and Technology Conference, 1994. Proceedings., 44th, 1-4 May 1994 Page(s): 22 -28

[Abstract] [PDF Full-Text (628 KB)] IEEE CNF

50 Thermal modeling and experimental characterization of the C4/surface-mount-array interconnect technologies *Kromann, G.B.;*

Electronic Components and Technology Conference, 1994. Proceedings., 44th , 1-4 May 1994
Page(s): 395 -402

[Abstract] [PDF Full-Text (604 KB)] IEEE CNF

1 <u>2 3 4 5 6 7 8 [Next]</u>

Home | Log-out | Journals | Conference Proceedings | Standards | Search by Author | Basic Search | Advanced Search | Join IEEE | Web Account | New this week | OPAC Linking Information | Your Feedback | Technical Support | Email Alerting | No Robots Please | Release Notes | IEEE Online Publications | Help | FAQ | Terms | Back to Top

Copyright @ 2003 IEEE - All rights reserved